300mA High PSRR, Low Noise LDO Regulator

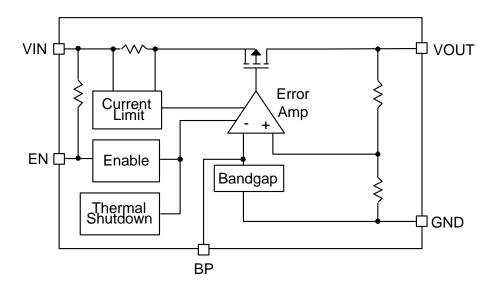
❖ GENERAL DESCRIPTION

The AX6609 is a 300mA, low guiescent, high PSRR, low noise and low dropout linear regulator. The Device includes pass element, error amplifier, band-gap, current-limit and thermal shutdown circuitry. The characteristics of low dropout voltage and less guiescent current make it good for some critical current application, for example, some battery powered devices. The typical quiescent current is approximately 90µA. In the shutdown mode, the maximum supply current is less than 1uA. Due to internal flexible design, result in extensively fixed output voltage versions 1.8V/2.5V/2.7V/3.3V. Built-in current-limit, Short current protection and thermal-shutdown functions prevent any fault condition from IC damage.

❖ FEATURES

- Input voltage range: 2.6V~6.0V
- Dropout voltage is 200mV at 150mA @ V_{OUT}=3.3V
- Guaranteed 300mA output current
- Low quiescent current is 90µA (typ.)
- Maximum supply current in shutdown mode <1uA
- Fixed Output voltage is 1.8V/2.5V/2.7V/3.3V
- High PSRR=70dB@120Hz, 65dB@1KHz
- Fast transient response
- Current limit and thermal shutdown protection
- Short circuit current fold-back
- Available in the TSOT-23-5L Package

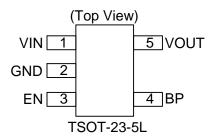
❖ BLOCK DIAGRAM





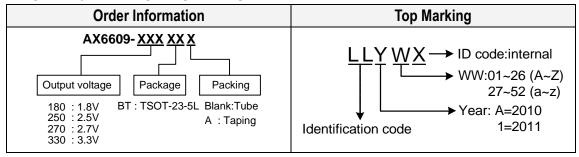
❖ PIN ASSIGNMENT

The package of AX6609 is TSOT-23-5L; the pin assignment is given by:



Name	Description			
VIN	Voltage input			
GND	Ground			
EN	Enable pin			
BP	Band gap			
VOUT	Output Voltage			

❖ ORDER/MARKING INFORMATION



Appendix

Part Number	Identification Code				
AX6609-1.8V	LG				
AX6609-2.5V	LQ				
AX6609-2.7V	LS				
AX6609-3.3V	La				

❖ ABSOLUTE MAXIMUM RATINGS (at T₄=25 °C)

* ADOCEOTE MAXIMOM NATINGO (at 1A-25 O)							
Characteristics		Rating	Unit				
V _{IN} Pin Voltage	V _{IN}	GND - 0.3 to GND + 6.5	V				
Output Voltage	V _{OUT}	GND - 0.3 to V _{IN} + 0.3	V				
Enable Voltage	V_{EN}	GND - 0.3 to GND + 6.5	V				
Power Dissipation	PD	400	mW				
Storage Temperature Range	T _{ST}	-40 to +150	°C				
Operating Temperature Range	T _{OP}	-40 to +85	°C				
Junction Temperature	TJ	-40 to +125	°C				
Thermal Resistance from Junction to case	θјς	180	°C/W				
Thermal Resistance from Junction to ambient	θЈА	250	°C/W				

Note: θ JA is measured with the PCB copper area of approximately 1 in²(Multi-layer). That need connect to GND pin.



❖ ELECTRICAL CHARACTERISTICS

T_A=25 °C (unless otherwise noted)

Characteristics	Symbol	Conditions		Min	Тур	Max	Units
Input Voltage	V_{IN}	I _{OUT} =10mA (Note1)		2.6	-	9	V
Output Voltage Accuracy (Note2)	ΔV _{OUT}	V _{IN} =V _{OUT} +0.1V to 6V I _{OUT} =1mA		-3	ı	+3	%
Quiescent Current	ΙQ	I _{OUT} =0mA, V _{IN} =5V		ı	90	ı	μΑ
	V _{DROP}	I _{OUT} =300mA	V _{OUT} =1.80V	-	8.0	1.0	V
Dropout Voltage			V _{OUT} =2.50V	ı	0.4	0.6	
			V _{OUT} =2.70V	-	0.38	0.5	
			V _{OUT} =3.30V	ı	0.36	0.5	
Current Limit (Note 3)	I _{LIMIT}	·		400	600	ı	mA
Short Circuit Current	I _{short}	V _{OUT} <1.0V		-	170	•	mA
Load Regulation (Note 4)	ΔV_{LOAD}	I _{OUT} =10m~300mA		ı	-	0.02	%/mA
Ripple Rejection	PSRR	C _{IN} =1µF, C _O =2.2uF,	F=120Hz	-	70	-	dB
		I _{OUT} =10mA	F=1KHz	-	65	-	
Enable Input Threshold	V _{ENH}			2.0	-	-	V
Enable Input Threshold	V_{ENL}			-	-	8.0	V
Enable Pin Current	I _{EH}	V _{EN} =V _{IN}		-	0.003	0.1	μΑ
Shutdown Current	I _{SD}	V _{IN} =5V, V _{EN} =0V		-	-	1	μΑ
Temperature Shutdown	Ts			-	150	-	°C
Temperature Shutdown Hysterisis	T _{SH}			-	30	-	°C

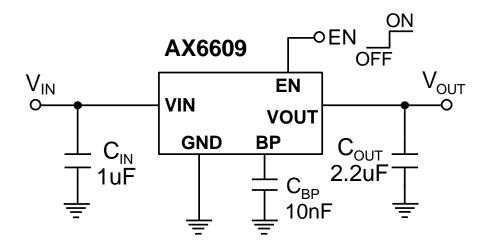
Note1: Minimum V_{IN} voltage is defined by output adds a dropout voltage.

Note2: V_{IN} minimum must larger than 2.6V.

Note3: Current limit is measured at constant junction temperature by using pulsed testing with a low ON time.

Note4: Regulation is measured at constant junction temperature by using pulsed testing with a low ON time.

*** APPLICATION CIRCUIT**



FUNCTION DESCRIPTIONS

A minimum of $2.2\mu F$ capacitor must be connected from V_{OUT} to ground to insure stability. Typically a large storage capacitor is connected from V_{IN} to ground to ensure that the input voltage does not sag below the minimum dropout voltage during the load transient response. This pin must always be dropout voltage higher than V_{OUT} in order for the device to regulate properly.

APPLICATION INFORMATION

Like any low-dropout regulator, the AX6609 requires input and output decoupling capacitors. The device is specifically designed for portable applications requiring minimum board space and smallest components. These capacitors must be correctly selected for good performance (see Capacitor Characteristics Section). Please note that linear regulators with a low dropout voltage have high internal loop gains which require care in guarding against oscillation caused by insufficient decoupling capacitance.

Capacitor Selection

Normally, use a 1 μ F capacitor on the input and a 2.2 μ F capacitor on the output of the AX6609. Larger input capacitor values and lower ESR (X5R, X7R) provide better supply-noise rejection and transient response. A higher- value output capacitor (10 μ F) may be necessary if large, fast transients are anticipated and the device is located several inches from the power source.

Input-Output (Dropout) Voltage

A regulator's minimum input-to-output voltage differential (dropout voltage) determines the lowest usable supply voltage. In battery-powered systems, this determines the useful end-of-life battery voltage. Because the device uses a PMOS, its dropout voltage is a function of drain-to source on-resistance, R_{DS (ON)}, multiplied by the load current:

$$V_{DROPOUT} = V_{IN} - V_{OUT} = R_{DS(ON)} \times I_{OUT}$$

Current Limit and Short-Circuit Protection

The AX6609 uses a current sense-resistor to monitor the output current. A portion of the PMOS output transistor's current is mirrored to a resistor such that the voltage across this resistor is proportional to the output current. Once the output current exceeds limit threshold, AX6609 would be protected with a limited output current. Further more, when the output is short to ground, the output current would be folded-back to a less limit.

Thermal Considerations

The AX6609 series can deliver a current of up to 300mA over the full operating junction temperature range. However, the maximum output current must be dated at higher ambient temperature to ensure the junction temperature does not exceed 125°C. With all possible conditions, the junction temperature must be within the range specified under operating conditions. Power dissipation can be calculated based on the output current and the voltage drop across regulator.

$$PD = (V_{IN} - V_{OUT}) I_{OUT}$$

The final operating junction temperature for any set of conditions can be estimated by the following thermal equation:

PD (MAX) =
$$(T_{J (MAX)} - T_A) / \theta_{JA}$$

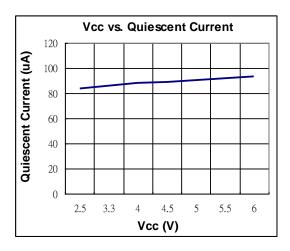
Where $T_{J \text{ (MAX)}}$ is the maximum junction temperature of the die (125°C) and T_A is the maximum ambient temperature. The junction to ambient thermal resistance (θ_{JA}) for TSOT23-5 package at recommended minimum footprint is 250°C/W.

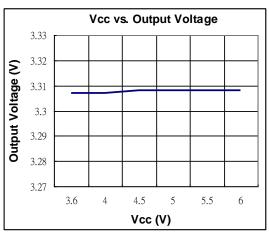
PCB Layout

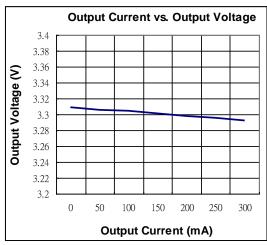
An input capacitance of $\cong 1\mu F$ is required between the AX6609 input pin and ground (the amount of the capacitance may be increased without limit), this capacitor must be located a distance of not more than 1cm from the input and return to a clean analog ground. Input capacitor can filter out the input voltage spike caused by the surge current due to the inductive effect of the package pin and the printed circuit board's routing wire. Otherwise, the actual voltage at the IN pin may exceed the absolute maximum rating. The output capacitor also must be located a distance of not more than 1cm from output to a clean analog ground. Because it can filter out the output spike caused by the surge current due to the inductive effect of the package pin and the printed circuit board's routing wire.

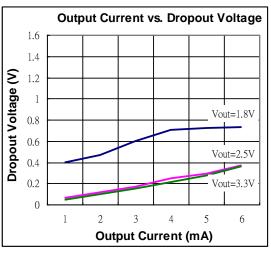


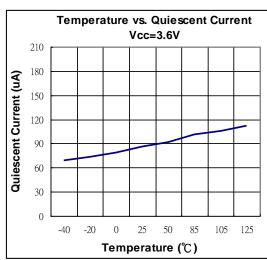
* TYPICAL CHARACTERISTICS

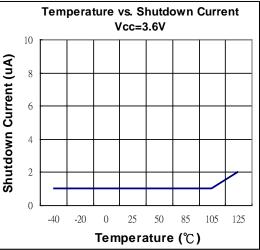






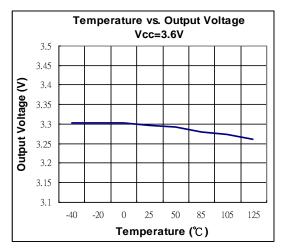


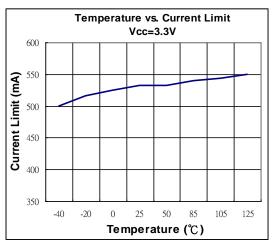


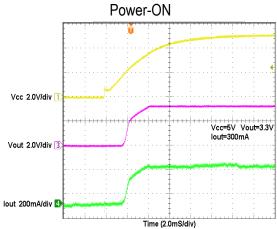


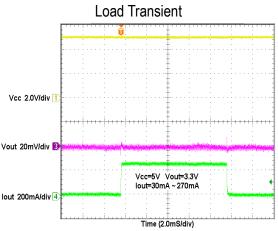


*** TYPICAL CHARACTERISTICS (CONTINUES)**



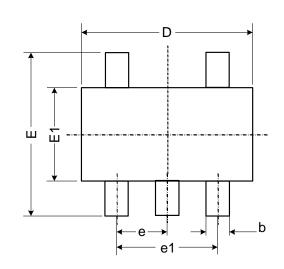


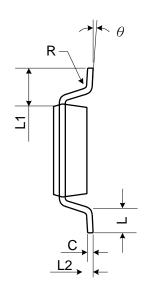


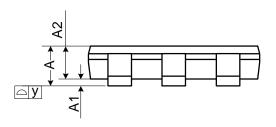




*** PACKAGE OUTLINES**







Symbol	Dime	ensions in Millin	Dimensions in Inches					
Symbol	Min.	Nom.	Max.	Min.	Nom.	Max.		
Α	-	-	1.10	-	-	0.043		
A1	0.00	-	0.10	0	-	0.004		
A2	0.70	0.90	1.00	0.028	0.035	0.039		
b	0.30	0.40	0.50	0.012	0.016	0.020		
С	0.08	0.14	0.20	0.003	0.006	0.008		
D	2.80	2.90	3.00	0.110	0.114	0.118		
E	2.60	2.80	3.00	0.102	0.110	0.118		
E1	1.50	1.60	1.70	0.059	0.063	0.067		
е		0.95 BSC.			0.037 BSC.			
e1		1.90 BSC.			0.075 BSC.			
L	0.30	0.45	0.60	0.012	0.018	0.024		
L1	0.60 REF.			0.024 REF.				
L2	0.25 BSC.			0.010 BSC.				
у	-	-	0.10	-	-	0.004		
R	0.10	-	-	0.004	-	-		
θ	0°	-	8°	0°	-	8°		

JECED outline: MO-193 AB